

## Contact

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## Top Skills

think-cell  
Pythorch  
Scaler

# Hiep Nguyen

Manager, AI Engineering  
Vietnam

## Summary

I'm a person who likes challenges and dealing with difficult problems.

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## Experience

Techcombank (TCB)  
Manager, AI Engineering  
January 2025 - Present (3 months)  
Ho Chi Minh City, Vietnam

Samsung Electronics HCMC CE Complex  
Lead Multimedia Engineer  
January 2024 - January 2025 (1 year 1 month)  
Ho Chi Minh City, Vietnam

Dynim  
4 years 10 months  
Lead AI Engineer  
September 2021 - December 2023 (2 years 4 months)  
Vietnam

Project: Stereo Camera for Autonomous Mobile Robots.

The project build the dynamic baseline Stereo Camera system based on Luxonis DepthAI platform for the AMR.

### Activities:

- Calibrate the Stereo Camera system : Camera-Camera and Camera-IMU calibration.
- Design and develop Stereo Camera functionalities, including: Stereo Depth Estimation, Spatial Object Detection, Spatial Object Tracking
- Design and develop "Follow Me" PoC application for the AMR.
- Optimize the solutions for the Intel Myriad VPU.

Senior AI Engineer  
July 2020 - September 2021 (1 year 3 months)

Vietnam

Project: SPARK Industrial Stereo Camera.

The project build the Stereo Camera system based on NXP i.MX 8M Plus platform for the industrial harsh environment.

Activities:

- Calibrate the Stereo Camera system : Camera-Camera and Camera-IMU calibration.
- Implement the software-based image signal processing application optimized by NPU.
- Design and develop the AI Camera SDK for end-to-end AI pipeline with CSI camera, inference and display.
- Optimize the YoloV5/YoloV8 models for iMX8MP NPU.

AI Engineer

March 2019 - July 2020 (1 year 5 months)

Vietnam

Project: Vital Signs camera.

Measuring heart rate, breathing rate with any webcam or camera based on Nvidia Jetson Nano platform.

Activities:

- Conduct data collection for heart rate and breathing rate datasets.
- Training and fine tuning ssd-mobilenet-v2 model for face detection and deploy on Nvidia Jetson Nano platform.
- Design and develop AI Camera SDK for end-to-end AI pipeline with USB camera, inference and display.

DEK Technologies

1 year 9 months

CBA Support Engineer

November 2018 - March 2019 (5 months)

Vietnam

Project: CBA Support Engineer.

The common component support engineer team is the interface for the application organizations to contact with issues and problems relating to the components.

Activities:

- Trouble shooting the problems to find out root cause about Core Middleware and related projects.
- Provide solution or work-around for the customer.
- Solving the problem or co-operate with designer to find out the solution.

Software Engineer

July 2017 - November 2018 (1 year 5 months)

Vietnam

Project : Core Middleware.

CoreMW is the project which is based on OpenSAF - a high availability framework and including software, performance, monitoring,... management functions. The whole project will provide functionality as high availability, scalability and independent components. Therefore the applications can reuse these functions for their project, not only reduce development time but also have high availability applications.

Activities:

- Development and maintenance for CoreMW application.
- Solving trouble shooting reports and provide solution or work-around for the customer.

FPT Software

Internship - on job training

December 2016 - March 2017 (4 months)

Project: E-commerce website.

This is an outsourcing project for a Japanese company to build an end-to-end e-commerce website and deployment on Azure.

Activities:

- Attending team tech-lead's training classes : client-server model, socket communication, using GIT for version controlling, etc...
- User experience testing to find out unexpected behavior or bugs of back-end and report to development team.
- Writing test cases for socket communication module using PHP.

## Education

Ho Chi Minh University of Technology

Bachelor of Engineering - BE, Electrical and Electronics

Engineering · (2013 - 2018)